Samsung Electronics Co., Ltd. 2//4-0/ dditional name(s) of conveying parties attached? [Yes No. Nature of conveyance: Assignment [Merger] Security Agreement [Change of Name] Other: xecution Date: February 6, 2001 and February 5, 2001 Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? [Name and address of party to whom correspondence oncerning document should be mailed: lame: William E. Winters	 2. Name and address of receiving party(ies) Name: Fairchild Korea Semiconductor Ltd. Internal Address: Street Address: 82-3 Dodang-Dong, Wonmi-Ku, Puchon-City, City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? Yes IN No ecution date of the application is: B. Patent No(s):
 Name of conveying party(ies): Samsung Electronics Co., Ltd. 2//4-0/ dditional name(s) of conveying parties attached? Yes No. Nature of conveyance: Assignment	 2. Name and address of receiving party(ies) Name: Fairchild Korea Semiconductor Ltd. Internal Address: Street Address: 82-3 Dodang-Dong, Wonmi-Ku, Puchon-City, City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: B. Patent No(s): ☐ Yes ⊠ No
Samsung Electronics Co., Ltd. 2//4-0/ dditional name(s) of conveying parties attached? [Yes No. Nature of conveyance: Assignment [Merger] Security Agreement [Change of Name] Other: xecution Date: February 6, 2001 and February 5, 2001 Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? [Name and address of party to whom correspondence oncerning document should be mailed: lame: William E. Winters	Name: Fairchild Korea Semiconductor Ltd. Internal Address: Street Address: 82-3 Dodang-Dong, Wonmi-Ku, Puchon-City, City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: B. Patent No(s): ☐ Yes ⊠ No
dditional name(s) of conveying parties attached? Yes No. Nature of conveyance: Assignment Merger Security Agreement Change of Name Other: Other: xecution Date: February 6, 2001 and February 5, 2001 Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? Name and address of party to whom correspondence oncerning document should be mailed: ame:	Internal Address: Street Address: 82-3 Dodang-Dong, Wonmi-Ku, Puchon-City, City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: B. Patent No(s):] Yes ⊠ No
Nature of conveyance: Assignment Merger Security Agreement Change of Name Other: Assignment xecution Date: February 6, 2001 and February 5, 2001 Application Number(s) or Patent Numbers. Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? Additional numbers attached? Name and address of party to whom correspondence oncerning document should be mailed: Additional numbers	Street Address: 82-3 Dodang-Dong, Wonmi-Ku, Puchon-City, City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: 1 B. Patent No(s): ☐ Yes ⊠ No
Assignment Merger Security Agreement Change of Name Other: Other: xecution Date: February 6, 2001 and February 5, 2001 Application Number(s) or Patent Numbers. Merger Application Number(s) or Patent Numbers. Merger A. Patent Application No(s): 08/742,754 Additional numbers attached? Merger Name and address of party to whom correspondence Merger Image: William E. Winters	City: Kyunggi-do Country: Republic of Korea ZIP: Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: B. Patent No(s): ☐ Yes ⊠ No
Security Agreement Change of Name Other: . xecution Date: February 6, 2001 and February 5, 2001 . Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? . Name and address of party to whom correspondence . oncerning document should be mailed: . ame: William E. Winters	Additional names and addresses attached? ☐ Yes ⊠ No ecution date of the application is: 301 B. Patent No(s): ☐ Yes ⊠ No
Other: ////////////////////////////////////	ecution date of the application is: B. Patent No(s):] Yes ⊠ No
J Other: xecution Date: February 6, 2001 and February 5, 2001 . Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached?	ecution date of the application is: B. Patent No(s):] Yes ⊠ No
xecution Date: February 6, 2001 and February 5, 2001 . Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached? . Name and address of party to whom correspondence oncerning document should be mailed: lame: William E. Winters	B. Patent No(s):
Application Number(s) or Patent Numbers. this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached?	B. Patent No(s):
this document is being filed together with a new application, the exe A. Patent Application No(s): 08/742,754 Additional numbers attached?	B. Patent No(s):
A. Patent Application No(s): 08/742,754 Additional numbers attached?	B. Patent No(s):
Additional numbers attached?]Yes 🛛 No
Additional numbers attached?]Yes 🛛 No
Name and address of party to whom correspondence oncerning document should be mailed:	
oncerning document should be mailed: lame: William E. Winters	A REAL PROPERTY AND A REAL
TOWNSEND AND TOWNSEND AND CREW LLP	7. Total fee (37 CFR 3.41):\$40.00
Two Embarcadero Center, 8 th Floor San Francisco, California 94111-3834	Enclosed Charge Fees to Deposit Account
(415) 576-0200	I Charge any additional fees associated with this paper or during the pendency of this application, or credit any overpayment, to
	deposit account.
1	8. Deposit account number: 20-1430
DO NOT USE T	THIS SPACE
. Statement and signature.	
To the best of my knowledge and belief, the foregoing is true riginal document.	e and correct and any attached copy is a true of copy of the
	$\left \begin{array}{c} \\ \\ \\ \end{array} \right = 2 \left \left \left \left \left \right \right \right \right \right $
William E. Winters Name of Person Signing	
	including cover sheet, attachments and document 3
	es 🗌 No
MB No. 0651-0011 (exp. 4/94) Do not detach	this portion
ail documents to be recorded with required cover to:	
Asst. Commission	
Box: Assig Washington, D	
·····	

PATENT REEL: 011565 FRAME: 0383 Forni PTO-1595 Recordation Form Cover Sheet Patents Only Page 2

- 1. Additional name(s) of conveying party(ies): (Continued from Page 1)
- 2. Additional name(s) and address(es) of receiving party(ies): (Continued from Page 1)
- 3. Additional application number(s) or patent number(s): (Continued from Page 1)

A. Patent Application No.(s)

B. Patent No.(s)

SF 150911 v1 SF 1189525 v1

> PATENT REEL: 011565 FRAME: 0384

34537634

ASSIGNMENT

ASSIGNMENT

WHEREAS, <u>SAMSUNG ELECTRONICS CO., LTD. of 416, Maetan-dong, Paldal-ku, Suwon, Kyunggi-do, Republic of</u> <u>Korea, (ASSIGNOR)</u> is the respective owner of the following U.S. patent application whose U.S. Application Serial No., Filing Date, Title, Assignment and Reel/Frame No. for recording of assignments from the respective inventor to ASSIGNOR are listed below:

U.S. APP. SERIAL NO.	FILING DATE	TITLE	REEL/FRAME NO.
08/742,754		Trench DMOS Device Having	8404/0868
		A High Breakdown Resistance	
		And Method Of Fabricating The Same	

WHEREAS, <u>Fairchild Korea Semiconductor Ltd. of 82-3</u>, <u>Dodang-Dong</u>, <u>Wonmi-Ku</u>, <u>Puchon-City</u>, <u>Kyunggi-do</u>, <u>Republic of Korea</u>, <u>ASSIGNEE</u> is desirous of obtaining the entire right, title and interest in, to and under the said applications and inventions therein:

NOW, THEREFORE, in consideration of the sum of One Dollar(\$1.00) to ASSIGNOR in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said Assigner, has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said inventions, and the said United States application and all divisions, renewals and commutations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said inventions in any country or countries foreign to the United States applications under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, is filed, as may be applicable; and all other said inventions is filed, as may be applicable; and all forms of industrial property or countries foreign to the United States and set over applications, renewals and reissues thereof;

AND ASSIGNOR HEREBY authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries forcign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR HEREBY covenants and agrees that it has full right to convey the entire interest herein assigned, and that it has not executed, or will not execute, any agreement in conflict herewith.

AND ASSIGNOR HEREBY further covenants and agrees that it will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to it respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

	IN_ TESTIMONY	WHEREOF,	ASSIGNOR	hercunto	scts	its , hand	and	scals	this	0	day
of .	, 2001.		1	nn				~			

ASSIGNOR: I

Scnior Vice President & General Manager

SAMSUNG ELECTRONICS CO., LTD.

	IN	TESTIMONY	WHEREOF,	ASSIGNEE	hereunto	sets	its	hand	and	scals	this	_
of	F	, 2001			5			•				

ASSIGNEE:

6. Ki

DEOK-JUNG KIM

President Fairchild Korea Semiconductor Ltd.

1

PATENT REEL: 011565 FRAME: 0385

5

_ day

RECORDED: 02/16/2001